

### Features

- Low drain-source on-resistance:  $R_{DS(ON)}=0.74\Omega(\text{typ})$
- Easy to control gate switching
- Enhancement mode:  $V_{th} = 2.0$  to  $4.0\text{V}$
- 100% avalanche tested
- Built-in ESD Diode
- RoHS compliant

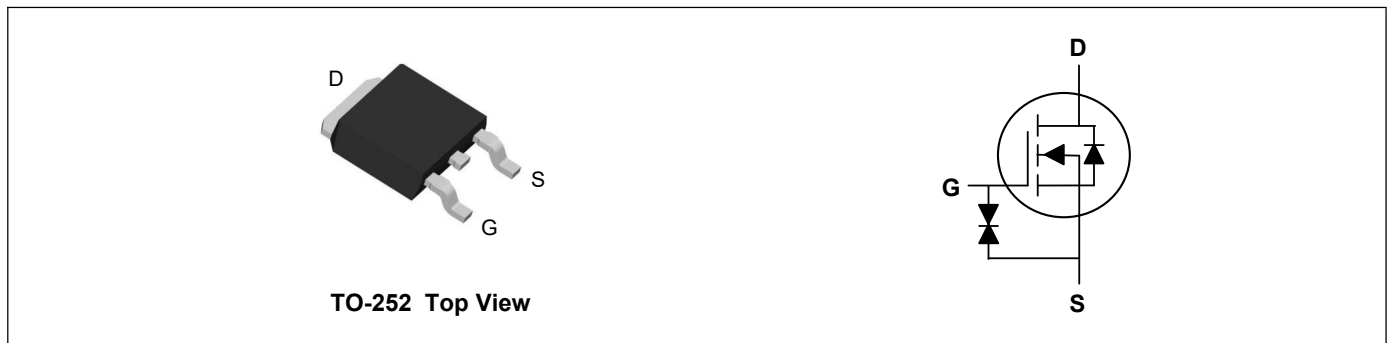
### Key Performance Parameters



Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	800	V
$R_{DS(ON),max}$	850	m $\Omega$
$I_D$	6.6	A
$Q_{g,typ}$	13.7	nC
$I_{DM}$	19.8	A

### Applications

- Switch Mode Power Supply (SMPS)
- TV power & LED Lighting Power
- AC to DC Converters
- Telecom



### Absolute Maximum Ratings( $T_C=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	800	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$I_D @ T_C=25^\circ\text{C}$	6.6	A
Continuous Drain Current <sup>1</sup>	$I_D @ T_C=100^\circ\text{C}$	4.2	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	19.8	A
Single Pulse Avalanche Energy <sup>4</sup>	EAS	84	mJ
Avalanche Current	$I_{AS}$	1.4	A
MOSFET dv/dt ruggedness, $V_{DS} = 0 \dots 400\text{V}$	dv/dt	50	V/ns
Reverse diode dv/dt <sup>3</sup> $V_{DS}=0 \dots 400\text{V}, I_{DS} \leq I_D$		15	
Total Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	66	W
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature Range	$T_J$	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-Ambient (Max)	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$
Thermal Resistance Junction-Case (Max)	$R_{\theta JC}$	1.9	$^\circ\text{C/W}$

**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=1mA$	800	---	---	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=1.6A$	---	740	850	$m\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=220\mu A$	2.0	---	4.0	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=800V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	1	$\mu A$
		$V_{DS}=800V, V_{GS}=0V, T_J=150^{\circ}\text{C}$	---	---	100	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 1$	$\mu A$
Total Gate Charge	$Q_g$	$V_{DD}=640V, V_{GS}=10V, I_D=2.8A$	---	13.7	---	nC
Gate-Source Charge	$Q_{gs}$		---	2.9	---	
Gate-Drain Charge	$Q_{gd}$		---	4.2	---	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=400V, R_G=25\Omega, I_D=2.8A$	---	23	---	ns
Rise Time	$T_r$		---	18	---	
Turn-Off Delay Time	$T_{d(off)}$		---	74	---	
Fall Time	$T_f$		---	17	---	
Input Capacitance	$C_{iss}$	$V_{DS}=500V, V_{GS}=0V, f=1MHz$	---	635	---	$\mu F$
Output Capacitance	$C_{oss}$		---	14.6	---	
Reverse Transfer Capacitance	$C_{rss}$		---	2.5	---	

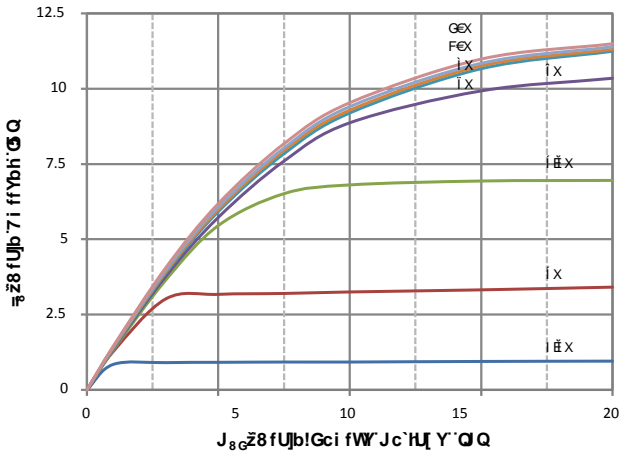
**Drain-Source Diode Characteristics**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current	$I_S$	$T_C=25^{\circ}\text{C}$	---	---	6.6	A
Pulsed Source Current	$I_{SM}$		---	---	19.8	A
Diode Forward Voltage	$V_{SD}$	$V_G=0V, I_S=2.8A, T_J=25^{\circ}\text{C}$	---	---	1.3	V
Reverse Recovery Time	$t_{rr}$	$V_R=400V, I_F=2.8A, di_F/dt=100A/\mu s$	---	170	---	ns
Reverse Recovery Charge	$Q_{rr}$		---	1.1	---	$\mu C$

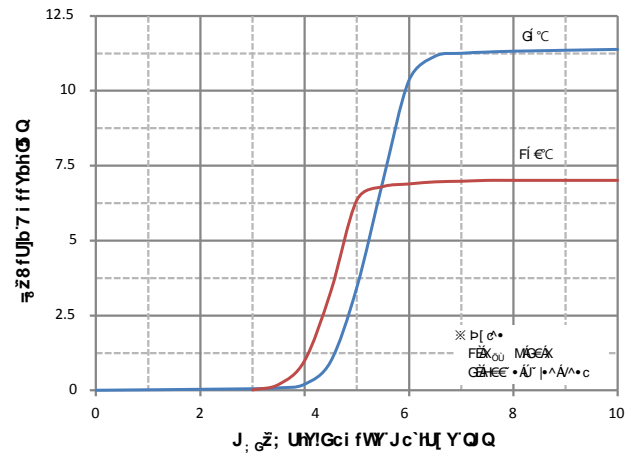
**Note:**

- Limited by  $T_{J,max}$ . Maximum Duty Cycle  $D = 0.50$
- Pulse width  $t_p$  limited by  $T_{J,max}$
- Identical low side and high side switch with identical  $R_G$
- $V_{DD}=50V, R_G=25\Omega, I_{AS}=1.4A$

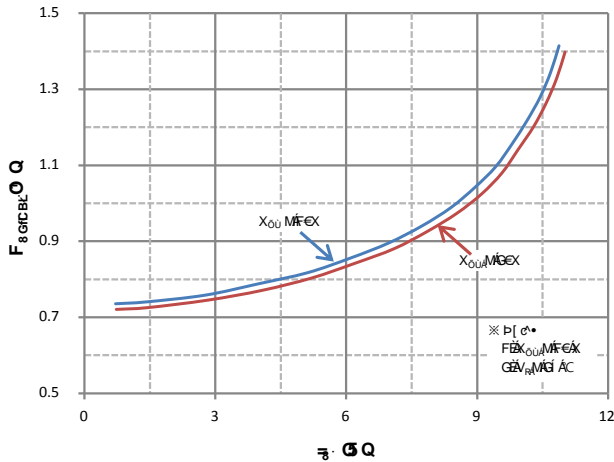
**Handl'WU 7\ UFUWYf]ghjVg**



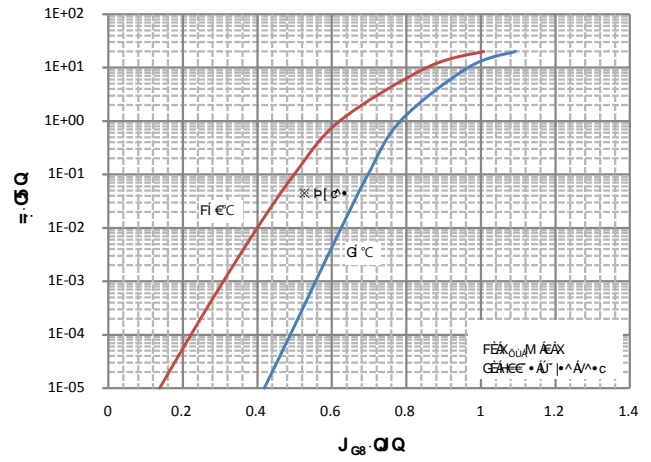
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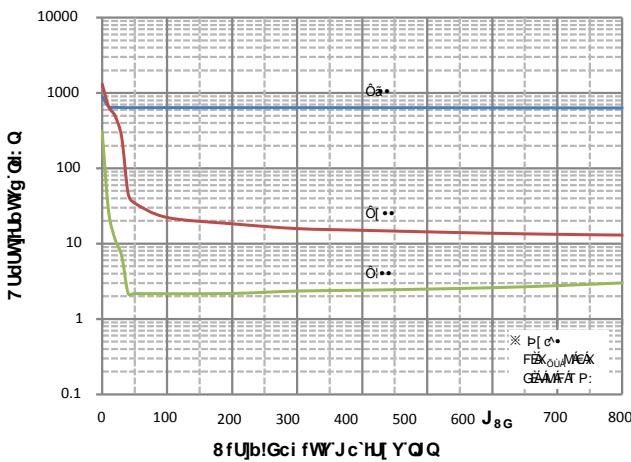
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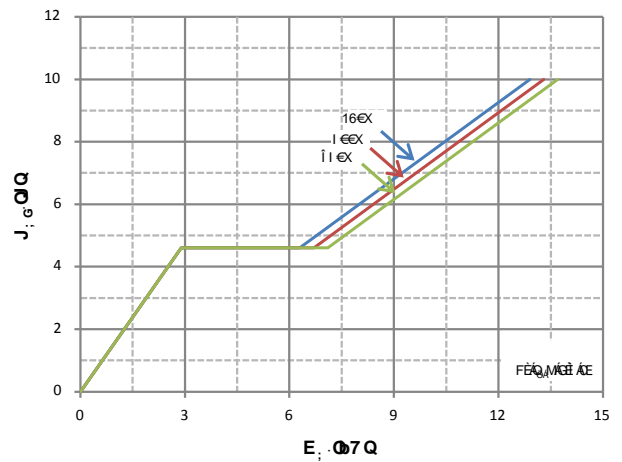
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: [[ i fY('6cXm8]cXY: cfk UFX'Jc'HU] Y JUF]Ujcb'k'Jh'Gci fW'7i ffYbh UbX'HYa dYUhi fY

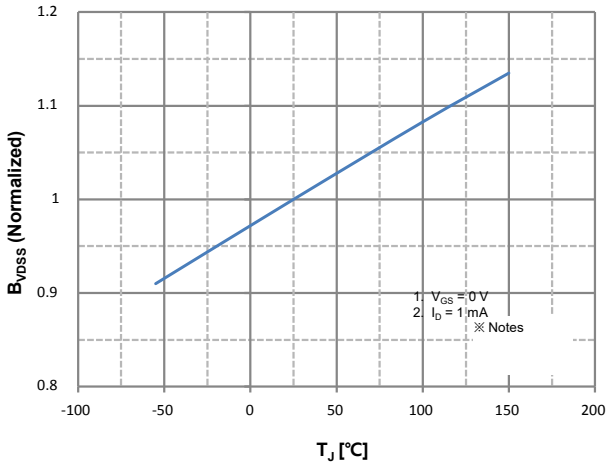


: [[ i fY)'7 UdUWYf]ghjVg

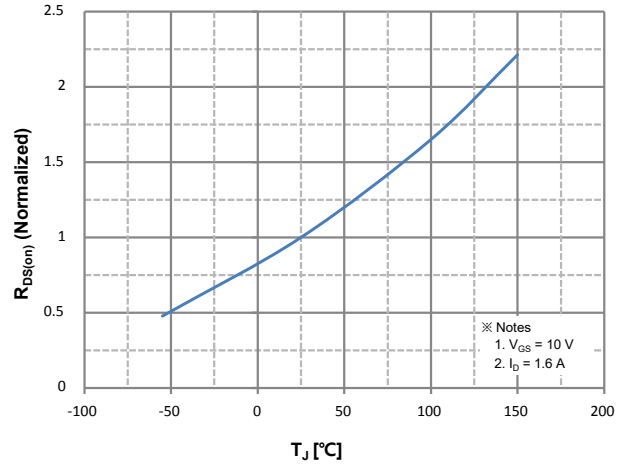


: [[ i fY\*'"; UH'7\ UF] Y7\ UFUWYf]ghjVg

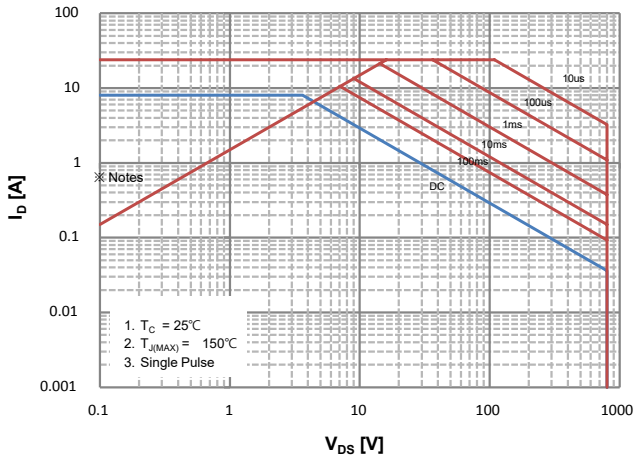
**800V Super Junction Power MOSFET**



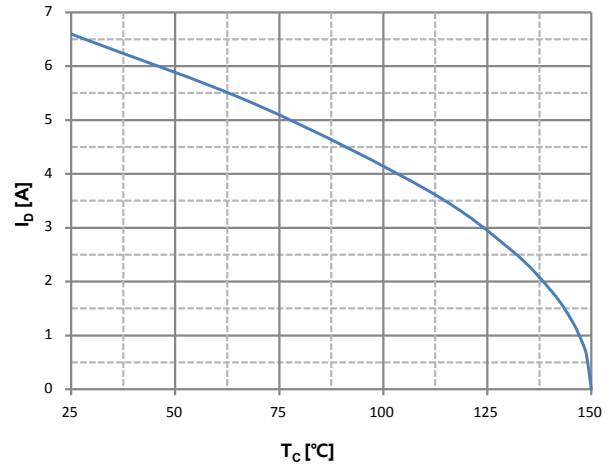
**Figure 7. Breakdown Voltage Variation vs. Temperature**



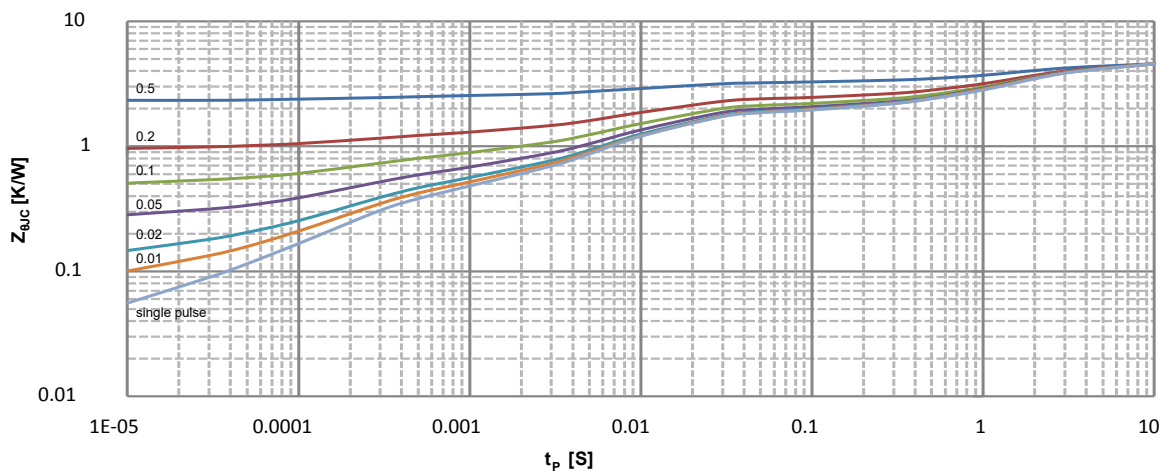
**Figure 8. On-Resistance Variation vs. Temperature**



**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs. Case Temperature**



**Figure 11. Transient Thermal Response Curve**

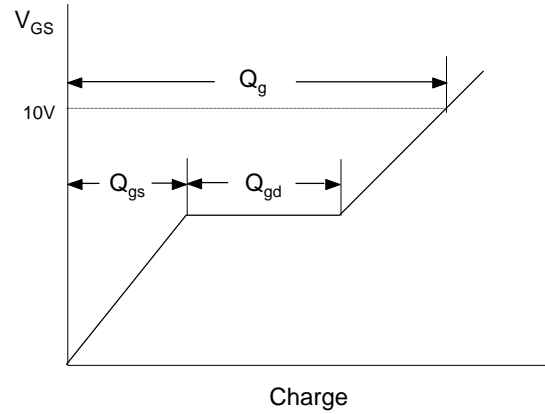
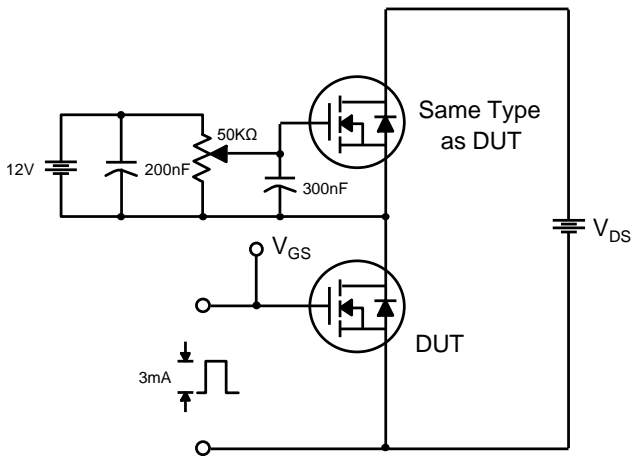


Fig 12. Gate Charge Test Circuit & Waveform

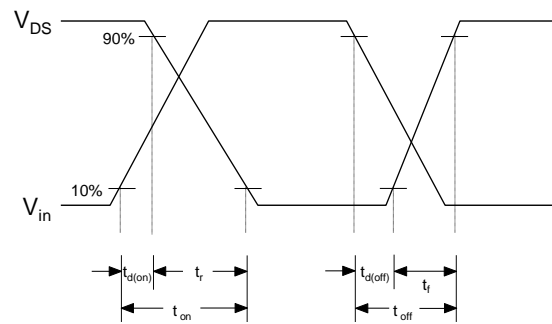
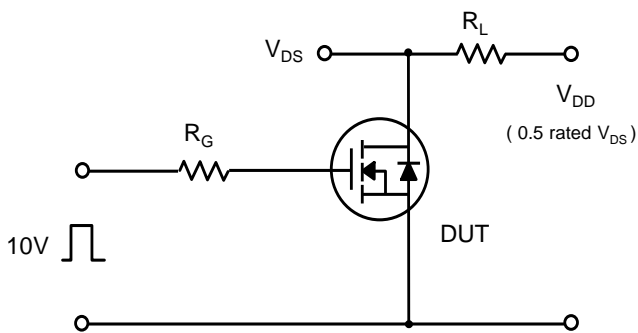


Fig 13. Resistive Switching Test Circuit & Waveforms

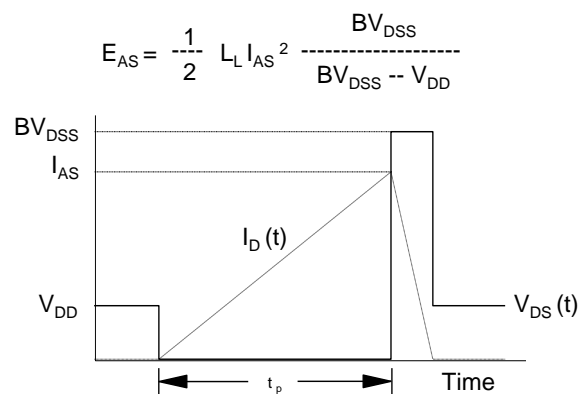
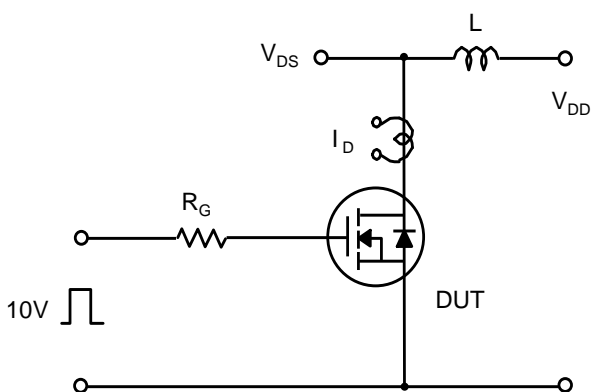
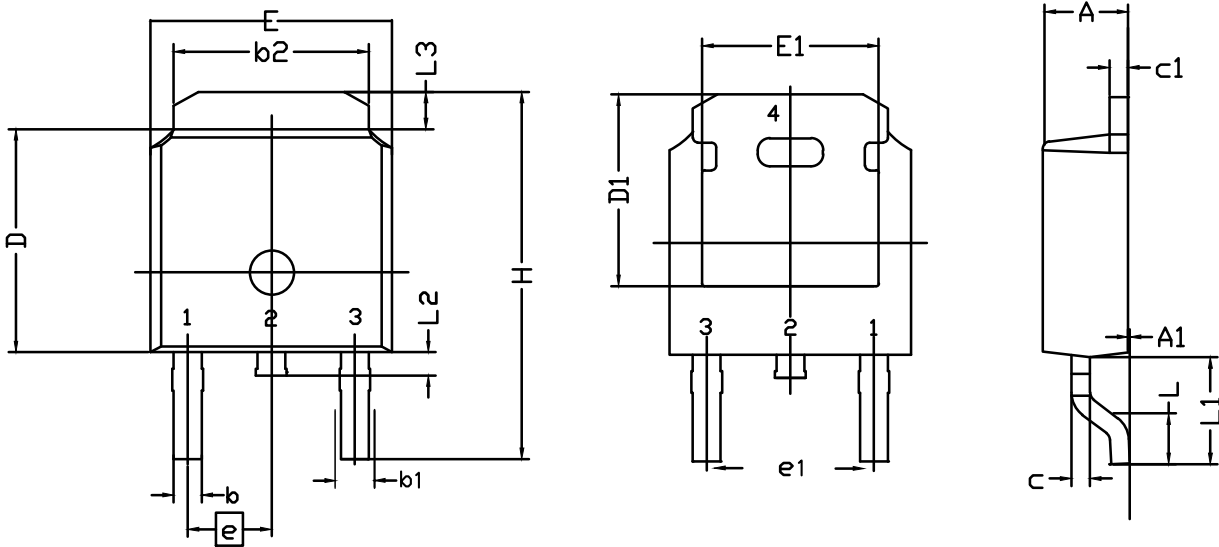


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

**TO-252 Package Outline Dimensions**



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	2.20	2.30	2.38	E	6.40	6.60	6.731
A <sub>1</sub>	0.00	0.10	0.20	E <sub>1</sub>	4.40	--	--
b	0.64	0.76	0.89	e	2.286 BSC		
b <sub>1</sub>	0.77	0.85	1.14	e <sub>1</sub>	4.572 BSC		
b <sub>2</sub>	5.00	5.33	5.46	H	9.40	10.00	10.40
c	0.458	0.508	0.610	L	1.40	1.52	1.77
C <sub>1</sub>	0.458	0.508	0.620	L <sub>1</sub>	--	2.743	--
D	5.98	6.10	6.223	L <sub>2</sub>	0.60	0.80	1.01
D <sub>1</sub>	5.20	5.25	5.38	L <sub>3</sub>	0.90	1.06	1.25